

COPPER FOIL FOR FINE PATTERN PRINTED CIRCUITS AND METHOD  
OF PRODUCTION OF SAME

ABSTRACT OF THE DISCLOSURE

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Copper foil for fine pattern printed circuits having  
a sufficient bond strength with a resin substrate,  
eliminating the problems of residual copper, erosion at  
the bottom portions of the circuit lines, etc. at the  
10 time of formation of fine patterns, and superior in heat  
resistance and electrical characteristics, comprising  
untreated copper foil roughening treated on its surface,  
wherein the untreated copper foil before roughening  
treatment is an electrodeposited copper foil having a  
15 surface roughness in terms of 10-point average roughness  
Rz not more than 2.5  $\mu\text{m}$  and a minimum distance between  
peaks of rough pyramid of at least 5  $\mu\text{m}$  or having further  
crystal grains of an average particle size of not more  
than 2  $\mu\text{m}$  exposed at the surface thereof, and a method of  
20 production of the same.